

REMARKS

Reconsideration of this application, as amended, is respectfully requested.

Claims 1-27 are pending. Claims 1-8 stand rejected. Claims 9-27 have withdrawn. Claims 1, 4, and 5 have been amended. Claims 6, 7 and 9-27 have been cancelled. Support for the amendments is found in the specification, the drawings, and in the claims as originally filed. Applicants submit that the amendments do not add new matter.

Restriction Requirements

The Applicants affirm election to prosecute claims 1-8 without traverse.

Rejections Under 35 U.S.C. § 112

The Examiner has rejected claims 4-7 under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which Applicants regard as the invention. The claims have been amended to particularly point out and distinctly claim the subject matter that the Applicants regard as the invention.

Rejections Under 35 U.S.C. 102 and 103

Claims 1, 2 and 4-8 stand rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,997,653 of Yamasaka (“Yamasaka”). Claims 1, 2 and 4-8 stand rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,589,338 of Nakamori et al. (“Nakamori”). Claims 1-8 stand rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,807,972 of Chiu et al. (“Chiu”). Claims 1, 2, and 4-8 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 6,713,122 of Mayer et al. (“Mayer”) in view of ASPA (Admitted State of Prior Art). The Examiner has rejected claims

1, 2, and 4-8 under 35 U.S.C. § 103(a) as being unpatentable over Mayer and ASPA. The Applicant respectfully traverses. The cited references fail to teach all of the elements of the Applicant's claims. In particular, the cited references fail to teach each of the elements of independent claim 1 of:

*A system for photoresist recovery comprising:
a nozzle to dispense a photoresist;
a bowl having an interior region and an interior surface;
a wafer platform disposed within the interior region of the bowl;
a wafer spindle coupled to the wafer platform, the wafer spindle to spin the wafer platform to propell an excess amount of a photoresist deposited upon a wafer placed upon the wafer platform to the interior surface of the bowl; and
a photoresist recovery container; and
a perimeter drain formed within the bowl such that the excess amount of photoresist propelled from the wafer proceeds through the perimeter drain to the photoresist recovery container.*

Specifically, the cited references fail to teach the elements of claim 1 that are unique to a system for photoresist recovery. These elements include "a nozzle to dispense a photoresist", "the wafer spindle to spin the wafer platform to propel an excess amount of photoresist deposited upon a wafer placed upon the wafer platform to the interior surface of the bowl", and "a photoresist recovery container". The nozzle to dispense a photoresist is unique to a system for photoresist recovery because the nozzle is specifically designed to dispense a viscous fluid such as a photoresist and would not be the same type of nozzle as would be used to dispense water or cleaning solutions. The wafer spindle to spin the wafer platform to propel an excess amount of photoresist is unique because it is designed to propel a viscous and heavy photoresist and not merely water or a cleaning solution. The photoresist recovery container is also unique to the photoresist recovery system because it is designed to

preserve a photoresist for reuse. The photoresist recovery container must therefore be airtight once sealed and be capable of blocking light if the photoresist is photosensitive.

The cited references fail to teach systems for photoresist recovery. Yamasaka teaches a washing-drying system for a semiconductor wafer that includes nozzles to dispense water, a cleaning solution, or a gas (Col. 5 lines 25 – 35.) Nakamori teaches a wafer cleaning device with a nozzle for supplying cleaning liquids. Chiu also teaches a wafer cleaning chamber. Mayer teaches an electroless plating apparatus. Each of these cited references fails to teach a system for photoresist recovery including elements unique to use with a photoresist. Therefore, the Applicants respectfully submit that the cited references, either individually or in combination, fail to teach all of the elements of independent claim 1 and the claims that depend upon and incorporate the elements of claim 1.

Petition for Extension of Time Pursuant to 37 C.F.R. 1.136(a)

Applicant respectfully petitions pursuant to 37 CFR 1.136(a) for a two-month extension of time to file this response to the Office Action mailed March 17, 2005. The extended period is set to expire on August 17, 2005. A check in the amount of \$450.00 is enclosed to cover the fee for a two-month extension of time.

Pursuant to 37 CFR 1.136(a)(3), applicant(s) hereby request and authorize the U.S. Patent and Trademark Office to (1) treat any concurrent or future reply that requires a petition for extension of time as incorporating a petition for extension of time for the appropriate length of time and (2) charge all required fees, including extension of time fees and fees under 37 CFR 1.16 and 1.17, to Deposit Account No. 02-2666.

Application No. 10/678,899
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If there are any additional charges, please charge Deposit Account No. 02-2666.

Respectfully submitted,

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